

MG031MD110006A

MOSFET Array

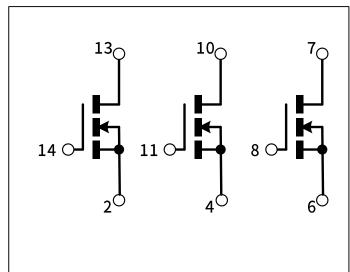
Feature

- MOSFET Array
- MOSFET(N-channel)
- High current capacity
- Low Ron
- Halogen free
- Pb free terminal
- RoHS:Yes

Outline



Equivalent circuit



Absolute maximum ratings $(Tc = 25^{\circ}C \text{ unless otherwise specified})$

MOSFET

| Item | Symbol | Conditions | Ratings | Unit |
|---------------------------------|------------------|--------------------------------|---------|------|
| Channel temperature | Tch | | 175 | °C |
| Drain-source voltage | V _{DSS} | | 60 | V |
| Gate-source voltage | V_{GSS} | | ±20 | V |
| Continuous drain current (DC) | I _D | | 110 | А |
| Continuous drain current (Peak) | I _{DP} | Pulse width 10μs, Duty = 1/100 | 440 | Α |
| Total power dissipation | P _T | | 154 | w |
| Single avalanche current | I _{AS} | Starting Tch=25°C Tch≦150°C | 44 | Α |
| Single avalanche energy | E _{AS} | Starting Tch=25°C Tch≦150°C | 232 | mJ |

Module

| Item | Symbol | Conditions | Ratings | Unit |
|---------------------|--------|-----------------|---------|-------|
| Storage temperature | Tstg | | -55~150 | °C |
| Mounting torque | TOR | Fixing screw M3 | 0.8 | N • m |

These are characteristics of the 1 chip unless otherwise specified.

MOSFET

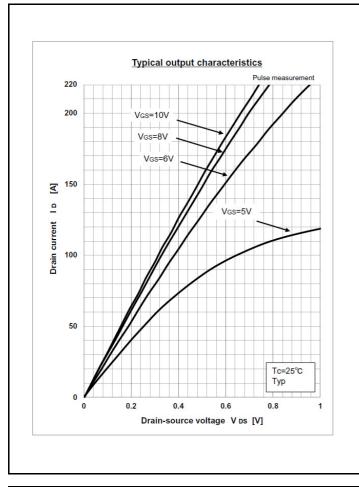
| Item | Symbol | Conditions | Ratings | | | Unit | |
|--|----------------------|---|--|------|------|------|------|
| | | contains | | Min. | Тур. | Max. | |
| Drain-source breakdown voltage | V _{(BR)DSS} | I _D =1mA, V _{GS} =0V | | 60 | _ | _ | V |
| Zero gate voltage drain current | I _{DSS} | V _{DS} =60V, V _{GS} =0V | | _ | _ | 1.0 | μΑ |
| Gate-source leakage current | I _{GSS} | V _{GS} =±20V, | V _{GS} =±20V, V _{DS} =0V | | _ | ±0.1 | μΑ |
| Static drain-source on-state | 5 | Chip | I _D =55A, V _{GS} =10V | | 2.4 | _ | mΩ |
| resistance | R _{DS(ON)} | Terminal | I _D =55A, V _{GS} =10V | _ | 2.9 | 3.8 | mΩ |
| Gate threshold voltage | V _{TH} | I _D =1mA, V _{DS} =10V | | 2.0 | 3.0 | 4.0 | V |
| Source-drain diode forward voltage | V _{SD} | Is=110A, V _{GS} =0V | | 1 | _ | 1.5 | V |
| Total gate charge | Qg | V -49V V -10V I -110A | | - | 96 | _ | nC |
| Gate to source charge | Qgs | V _{DD} =48V, V _{GS} =10V, I _D =110A (Electrical characteristics of discrete | _ | 25 | _ | | |
| Gate to drain charge | Qgd | MOSFET device) | | - | 32 | _ | |
| Input capacitance | Ciss | | | _ | 5535 | _ | |
| Reverse transfer capacitance | Crss | | GS=0V, f=1MHz Gracteristics of discrete MOSFET device) | - | 262 | _ | pF |
| Output capacitance | Coss | (Electrical characteristics of discrete MOSFET device) | | _ | 582 | _ | |
| Turn-on delay time | td(on) | | | _ | 10 | _ | - ns |
| Rise time | tr | ID=55A, VDD=30V, RL=0.55 Ω , Rg=0 Ω , VGS(+)=10V, VGS(-)=0V (Electrical characteristics of discrete MOSFET device) | - | 54 | _ | | |
| Turn-off delay time | td(off) | | _ | 60 | _ | | |
| Fall time | tf | (Lieutheat and deterrising of discrete most ET device) | | _ | 56 | _ | |
| Source-drain diode reverse recovery time | trr | -IF=110A, VGS=0V, di/dt=100A/μs | | _ | 37 | _ | ns |
| Source-drain diode reverse recovery charge | Qrr | | | _ | 61 | _ | nC |

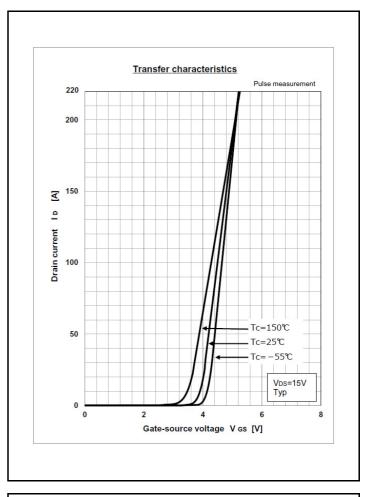
Module

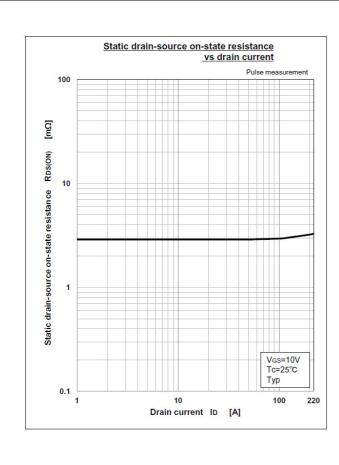
| Item | Symbol | Conditions | Ratings | | | Unit | |
|--------------------|---------------|--|---------|------|------|------|--|
| | | | Min. | Тур. | Max. | | |
| Thermal resistance | $R_{th(j-c)}$ | Junction to case | I | - | 0.97 | | |
| | $R_{th(j-l)}$ | Junction to lead | - | _ | 1.41 | | |
| | | Junction to lead, With insulating sheet, Thickness 0.3mm, Thermal conductivity 3.9W/mK | _ | _ | 2.16 | °C/W | |

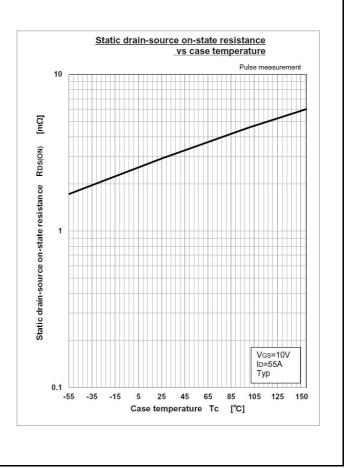
Note: Thermal resistance was measured at Q1

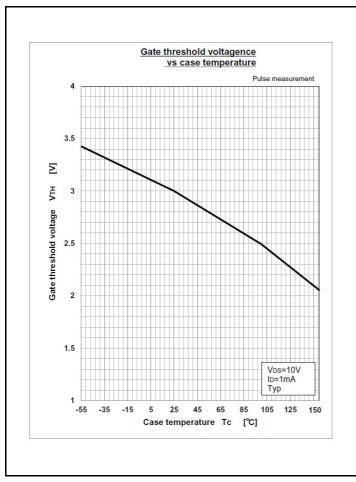
CHARACTERISTIC DIAGRAMS

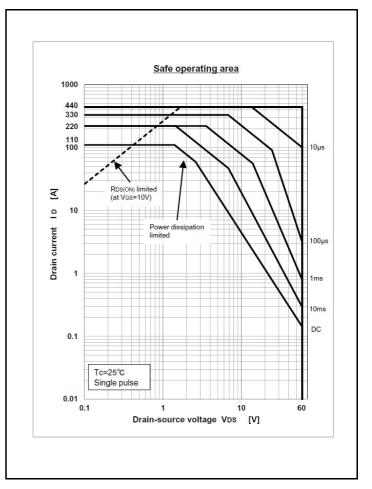


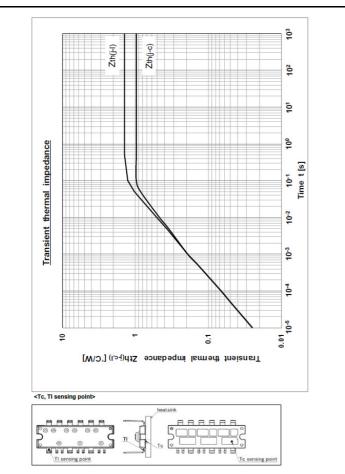


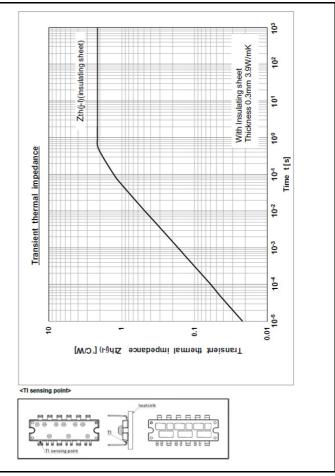


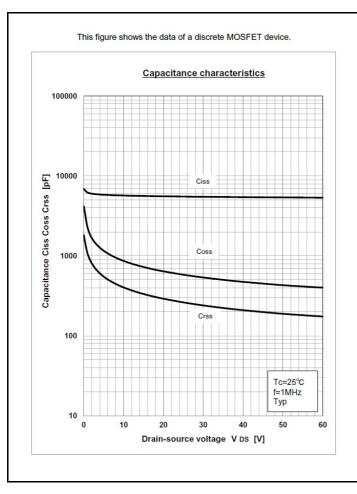


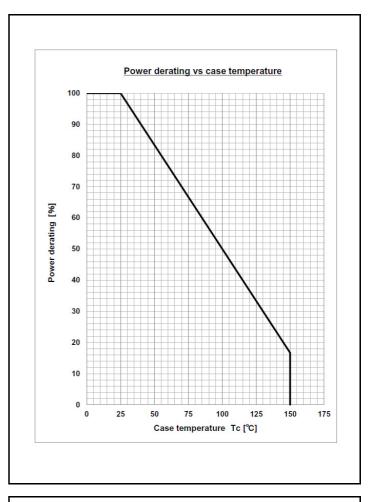


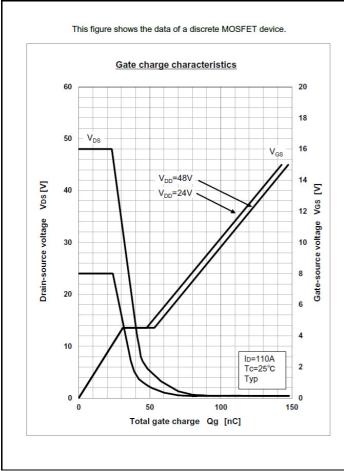


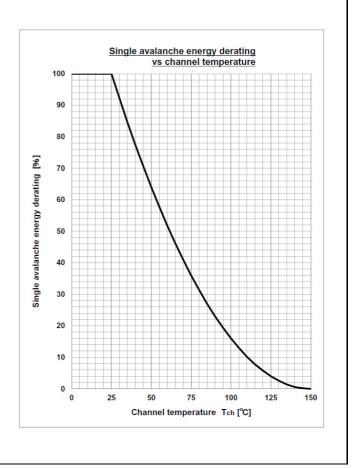








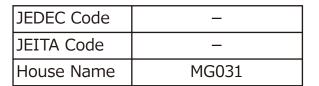


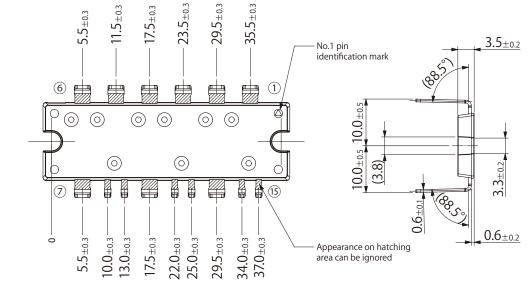


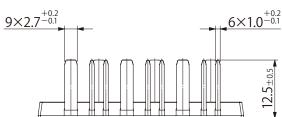
Package Outline-Dimensions

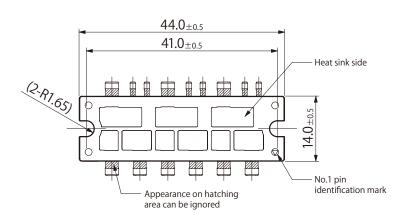
unit:mm

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